

**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION**ATTORNEY DOCKET NO. 70030280

As a below named inventor, I hereby declare that:

My residence/post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**METHOD OF FABRICATING A PACKAGING DEVICE FOR SEMICONDUCTOR DIE, AND  
SEMICONDUCTOR DEVICE INCORPORATING SAME**

the specification of which is attached hereto unless the following box is checked:

( ) was filed on \_\_\_\_\_ as US Application Serial No. or PCT International Application  
Number \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

**Foreign Application(s) and/or Claim of Foreign Priority**

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor(s) certificate listed below and have also identified below any foreign application for patent or inventor(s) certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE FILED	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			YES: _____ NO: _____
			YES: _____ NO: _____

**Provisional Application**

I hereby claim the benefit under Title 35, United States Code Section 119(e) of any United States provisional application(s) listed below:

APPLICATION SERIAL NUMBER	FILING DATE

**U. S. Priority Claim**

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NUMBER	FILING DATE	STATUS (patented/pending/abandoned)

**POWER OF ATTORNEY:**

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number 022878Place Customer  
Number Bar Code  
Label here

Send Correspondence to:  
**AGILENT TECHNOLOGIES, INC.**  
 Legal Department, DL429  
 Intellectual Property Administration  
 P.O. Box 7899  
 Loveland, Colorado 80537-0899

**Direct Telephone Calls To:**

Ian Hardcastle  
 (650) 485-3015

I hereby declare that all statements made herein of my own knowledge are true and that all statements made in information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Kong Weng LeeCitizenship: MalaysianResidence: Lehat Court 48-2-1 Jalan Sekolah La Salle, 10450 Penang, MalaysiaPost Office Address: Same as Residence

Inventor's Signature

Date

Rev 01/02 (DecPwr)

(Use Page Two For Additional Inventor(s) Signature(s))

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**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION (continued)**ATTORNEY DOCKET NO. 70030260

Full Name of # 2 joint inventor: Kee Yean Ng Citizenship: Malaysian  
Residence: 6, Halaman Kikik, Taman Inderawasih, 13600 Prai, Penang, Malaysia  
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Inventor's signature: [Signature] Date: June 26, 2003

Full Name of # 3 joint inventor: Yew Cheong Kuan Citizenship: Malaysian  
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Inventor's signature: [Signature] Date: June 26, 2003

Full Name of # 4 joint inventor: Gin Ghee Tan Citizenship: Malaysian  
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Inventor's signature: [Signature] Date: June 26, 2003

Full Name of # 5 joint inventor: Cheng Why Tan Citizenship: Malaysian  
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Post Office Address: Same as Residence Penang, Malaysia  
Inventor's signature: [Signature] Date: June 26, 2003

Full Name of # 6 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full Name of # 7 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_

Full Name of # 8 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's signature: \_\_\_\_\_ Date: \_\_\_\_\_